LISTING OF THE CLAIMS:

A listing of the claims is presented below.

Claims 1-10. (Cancelled)

11. (Original) A curable composition comprising:

(a) an epoxy resin;

(b) a latent fluxing agent which liberates a phenolic compound or a carboxylic acid containing compound when heated above 140°C; and

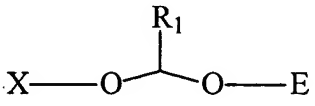
(c) a compound for effecting cure of the epoxy resin.

12. (Original) The composition of claim 11, wherein the latent fluxing agent is an α-alkoxyalkyl ester of a carboxyl-containing compound.

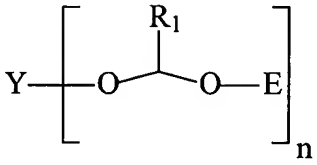
13. (Original) The composition of claim 11, wherein the latent fluxing agent is an α-alkoxyalkyl phenyl ether.

14. (Original) The composition of claim 11, wherein the latent fluxing agent comprises a reaction product of a carboxylic acid and a vinyl ether.

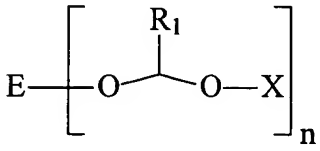
15. (Original) The composition of claim 11, wherein the latent fluxing agent comprises a composition selected from a compound having one or more of the following structures I through VI:



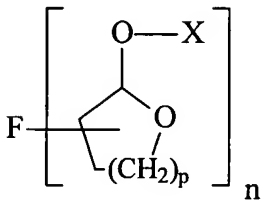
I



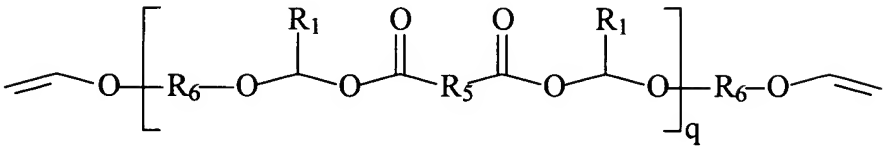
II



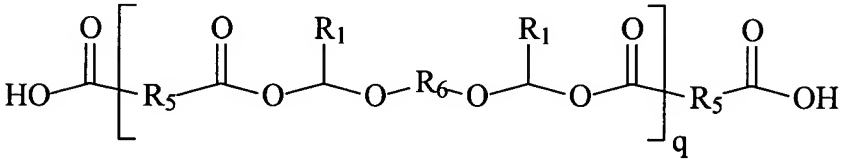
III



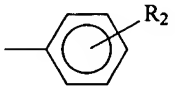
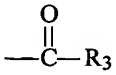
IV

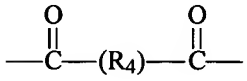
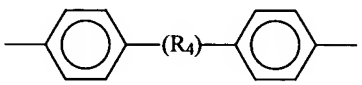


V



VI

wherein X denotes  or  ;

Y denotes  or  ;

E denotes an organic group derived from a 1-alkenyl ether and may be a hydrocarbon, ether, thioether, ester, thioester, carbamate, amide, or a combination of these groups;

F denotes an organic group fragment derived from a multifunctional 1-cycloalkenyl ether in which the cyclic ether groups are linked though F, and may be a hydrocarbon, ether, thioether, ester, thioester carbamate, amide, or a combination of these groups;

R_1 represents a C_1-C_6 alkyl group;

R^2 and R^3 are independently selected from hydrogen, substituted or unsubstituted linear or branched C_{1-22} alkyl, aryl, alkaryl, cycloalkyl, alkoxy and phenyl;

R_4 is substituted or unsubstituted linear or branched C_{1-22} alkylene, alkenylen, arylene, alkylenearyl, cycloalkylene, alkyleneoxy and phenylene;

R_5 and R_6 are independently selected from linear or branched C_{1-22} alkylene, alkenylene, arylene, alkylenearyl, cycloalkylene, alkyleneoxy and phenylene;

n is an integer from 2-30; p represents the integer 1 or 2 and q is an integer from 5-30.

16. (Original) The composition of claim 15, wherein the groups E and F include a reactive group selected

from the group consisting of oxirane, thiirane, hydroxyl, amino and mercapto.

17. (Original) The composition of claim 11, wherein the epoxy resin in (a) is one or more selected from the group consisting of bisphenol-A-type epoxy resin, bisphenol-F-type epoxy resin, phenol novolac-type epoxy resin, cresol novolac-type epoxy resin, polyepoxy compounds based on aromatic amines and epichlorohydrin, polyglycidyl derivatives of phenolic compounds, polyglycidyl derivatives of phenol-formaldehyde novolacs, polyglycidyl adducts of amines, aminoalcohols and polycarboxylic acids.

18. (Original) The composition of claim 11 wherein the compound for effecting cure of the epoxy resin in (c) comprises an epoxy curing agent or catalyst selected from the group consisting of anhydride compounds, amine compounds, amide compounds, imidazole compounds, polyfunctional phenols, carboxylic acids, thiols, and mixtures thereof.

19. (Original) The composition of claim 11, wherein the compound for effecting cure of the epoxy resin in (c) is 1,8-diazabicyclo[5.4.0]undec-7-ene.

Claims 20-22. (Cancelled)

23. (Original) The composition of claim 11 further comprising an inorganic filler material.

24. (Original) The composition of claim 23, wherein the inorganic filler material is one or more selected from the group of materials constructed of or containing reinforcing silicas, aluminum oxide, silicon nitride, aluminum nitride, silica-coated aluminum nitride and boron nitride.

25. (Original) A thermoset resin comprising a reaction product of the composition of claim 11.

26. (Original) A one component curable composition comprising:

(a) from about 15 percent to about 75 percent, based on the total weight of the composition, of an epoxy resin;

(b) from about 10 percent to about 70 percent, based on the total weight of the composition, of a thermally labile compound selected from the group consisting of (a) an

α-alkoxyalkyl ester reaction product of a carboxylic acid and a vinyl ether, and (b) an α-alkoxyalkyl phenyl ether reaction product of a phenolic acid and a vinyl ether;

(c) a compound for effecting cure of the epoxy resin selected from an epoxy curing agent in an amount of from about 0.15 to about 1.5 equivalents per equivalent of epoxide, or an epoxy curing catalyst in an amount of from about 0.02 percent to about 20 percent by weight of the epoxy component, or combinations thereof;

(d) from about 1 percent to about 70 percent, based on the total weight of the composition, of an inorganic filler material; and

(e) optionally, from about 1 percent to about 20 percent, based on the total weight of the composition, of an epoxy resin adduct of a carboxyl terminated toughening agent.

27. (Original) The composition of claim 26, wherein the thermally labile compound (b) includes one or more functional groups capable of reacting into a cured epoxy composition.

28. (Original) The composition of claim 27, wherein the thermally labile compound (b) includes an epoxy functional group.

Claims 29-39. (Cancelled)